

Marking Information

Site 1:



T5 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2013	 2019	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	Α	 G	Н		J	K	L	М	N	0	Р

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Site 2:



T5 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: H = 2020) W = Week (ex: a = week 27; z represents week 52 and 53) X = Internal code (ex: U = Monday)

Date Code Key

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028
Code	0	1	2	3	4	5	6	7	8

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	Х	Υ	Z



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage		V _{DSS}	50	V	
Gate-Source Voltage			V _{GSS}	±16	V
Continuous Prain Current (Note 6) // = 10)/	Steady State	T _A = +25°C T _A = +70°C	I _D	9.1 7.3	А
Continuous Drain Current (Note 6) V _{GS} = 10V	t<10s	T _A = +25°C T _A = +70°C	I _D	11.5 9.2	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	o)		I _{DM}	60	Α
Continuous Source-Drain Diode Current	Is	2.2	Α		
Avalanche Current (Note 7) L = 0.1mH	I _{AS}	14.4	Α		
Avalanche Energy (Note 7) L = 0.1mH			E _{AS}	10.4	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Units	
Total Bower Dissipation (Nato 5)	T _A = +25°C	0	0.82	W	
Total Power Dissipation (Note 5)	T _A = +70°C	P _D	0.52		
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	153	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	96		
Total Bower Dissipation (Note 6)	T _A = +25°C	6	1.97	W	
Total Power Dissipation (Note 6)	T _A = +70°C	P_D	1.2	۷V	
Thermal Peciatones, Junction to Ambient (Note 6)	Steady State	D	67	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	42		
Thermal Resistance, Junction to Case (Note 6)	Steady State	$R_{ heta JC}$	14		
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)						-	
Drain-Source Breakdown Voltage	BV _{DSS}	50	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μΑ	$V_{DS} = 40V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS	_	_	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	$V_{GS(TH)}$	0.5	1	2.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance			10.5	15	mΩ	$V_{GS} = 10V, I_D = 8A$	
Static Dialit-Source Off-Resistance	R _{DS(ON)}		14	23	111122	$V_{GS} = 4.5V, I_D = 6A$	
Diode Forward Voltage	V _{SD}	_	0.7	1.0	V	V _{GS} = 0V, I _S = 5A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{ISS}	1	902.7	_), OEV), OV	
Output Capacitance	Coss		301.4	_	pF	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1 0MHz	
Reverse Transfer Capacitance	C _{RSS}	_	15.2	_		1 - 1.01011 12	
Gate Resistance	R _G	_	1.9	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_{G}	_	6.1	_			
Total Gate Charge (V _{GS} = 10V)	Q_{G}	_	14	_	nC	V 05V I 0A	
Gate-Source Charge	Q _{GS}	_	2.4	_	IIC	$V_{DS} = 25V, I_D = 8A$	
Gate-Drain Charge	Q_GD	_	1.6	_			
Turn-On Delay Time	t _{D(ON)}	_	2.8	_			
Turn-On Rise Time	t _R		5.1	_		$V_{DS} = 25V, V_{GS} = 10V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	10.6	_	ns	$R_G = 3\Omega, I_D = 8A$	
Turn-Off Fall Time	t _F		2.7	_	1		
Reverse Recovery Time	t _{RR}	_	18.9	_	ns	I _F = 8A, di/dt = 100A/μs	
Reverse Recovery Charge	Q _{RR}		9.2	_	nC	I _F = 8A, di/dt = 100A/μs	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

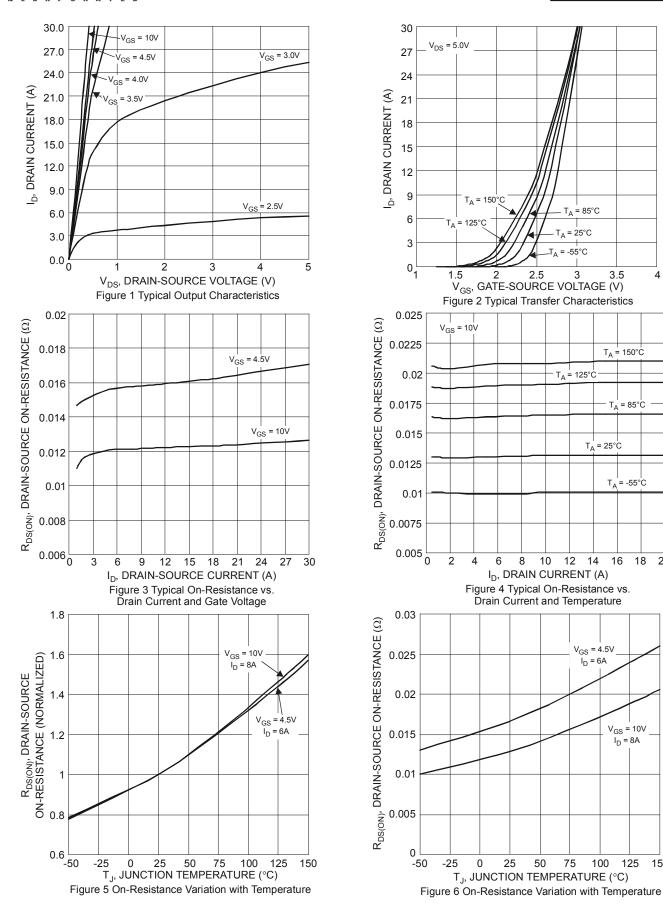
 $[\]hbox{6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1 inch square copper plate}.$

^{7.} I $_{AS}$ and E $_{AS}$ rating are based on low frequency and duty cycles to keep T_{J} = +25°C.

^{8.} Short duration pulse test used to minimize self-heating effect.

^{9.} Guaranteed by design. Not subject to product testing.







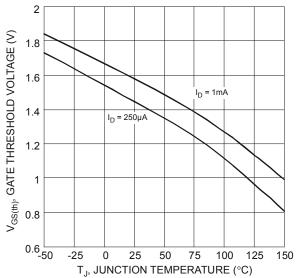


Figure 7 Gate Threshold Variation vs. Ambient Temperature

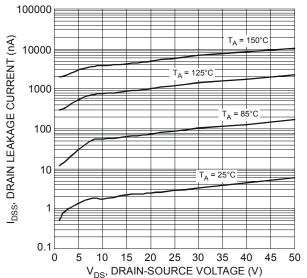
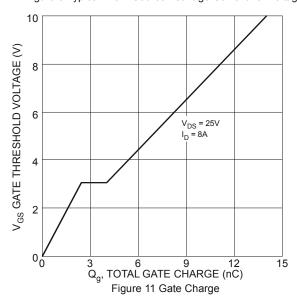
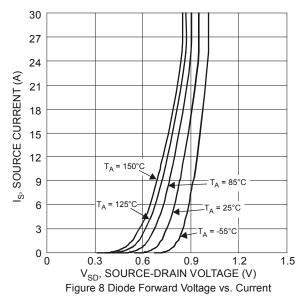
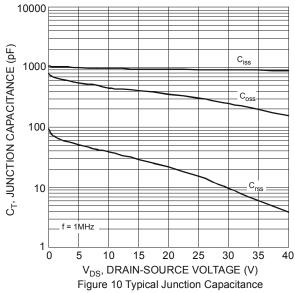
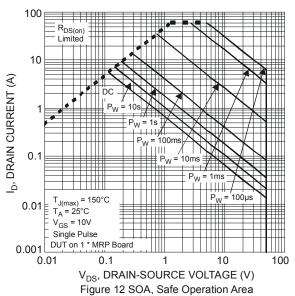


Figure 9 Typical Drain-Source Leakage Current vs. Voltage

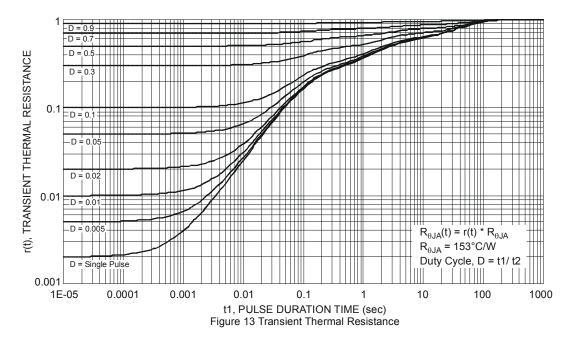










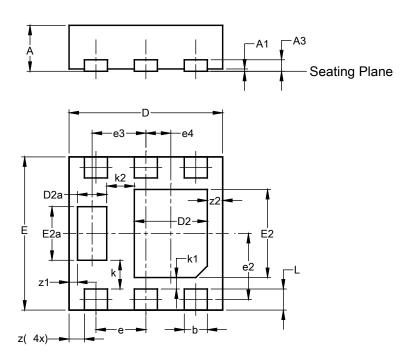




Package Outline Dimensions

 $Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

U-DFN2020-6 (Type F)

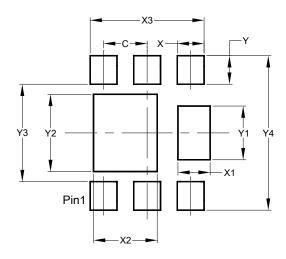


	U-DFN2020-6								
	(Type F)								
Dim	Min								
Α	0.57 0.63 0.60								
A 1	0.00	0.00 0.05 0.03							
A3	-	-	0.15						
b	0.25	0.35	0.30						
D	1.95	2.05	2.00						
D2	0.85	1.05	0.95						
D2a	0.33	0.43	0.38						
Е	1.95 2.05 2.00								
E2	1.05 1.25 1.15								
E2a	0.65 0.75 0.70								
е		0.65 BS	_						
e2	().863 BS	SC SC						
е3		0.70 BS	С						
e4	().325 BS	SC SC						
k		0.37 BS	С						
k1		0.15 BS	С						
k2		0.36 BS	С						
L	0.225 0.325 0.275								
Z	0.20 BSC								
z1	0.110 BSC								
z2		0.20 BS	_						
All C	Dimens	ions in	mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
С	0.650
X	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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